


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  DUNS number: 330866844  -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany  Declarations authorised by:  Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 May 2009 [Approved on 27 February 2026, 14:57 GMT]

## Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	4.8%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	3.57%	SILVER, ELEMENTAL	7440-22-4	2.5%
			Tin elemental	7440-31-5	5%
			Elemental lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	25.92%	Carbon black	1333-86-4	0.85%
			Phenol, polymer with formaldehyde	9003-35-4	1.15%
			Silicon Dioxide	7631-86-9	4%
			Epoxy resin 89	26335-32-0	7%
			Quartz sand	60676-86-0	87%
Inner preparation	Wrought aluminium alloys	3.87%	ALUMINUM, ELEMENTAL	7429-90-5	100%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.72%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	5.81%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	55.31%	Elemental iron	7439-89-6	2.5%
			COPPER, ELEMENTAL	7440-50-8	97.5%

**Attached parts list**

Part number	Part name	Part Mass	Part Mass UoM
QFN5x6 H-Free Al Cu	Diode / Transistor SMD	0.103	g

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